### STTH1004



Custom Data

# 57

### Main product characteristics

I <sub>F(AV)</sub>	10 A
V <sub>RRM</sub>	400 V
t <sub>rr</sub> (typ)	15 ns
Тj	175° C
V <sub>F</sub> (typ)	1.15 V

#### Features and benefits

- Ultrafast recovery
- Low power losses
- High surge capability
- Low leakage current
- High junction temperature

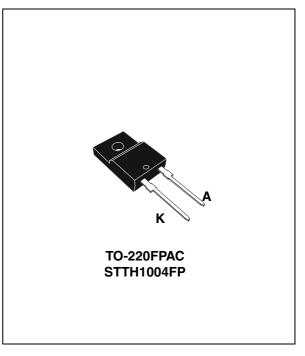
#### Description

The **STTH1004** is an Ultrafast Recovery Power Rectifier dedicated to **energy recovery in PDP application**.

It is especially designed for clamping function in energy recovery block.

The compromise between forward voltage drop and recovery time offers optimized performances.

Table 1. Absolute ratings (limiting values)



#### Order codes

Part Numbers	Marking
STTH1004FP	STTH1004

Symbol	Parameter	Value	Unit	
V <sub>RRM</sub>	Repetitive peak reverse voltage	400	V	
I <sub>F(RMS)</sub>	RMS forward current			А
I <sub>F(AV)</sub>	Average forward current	10	А	
I <sub>FSM</sub>	Surge non repetitive forward current $t_p = 10 \text{ m}$	100	А	
T <sub>stg</sub>	Storage temperature range	-65 to + 175	°C	
Тj	Maximum operating junction temperature	175	°C	

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### 1 Characteristics

#### Table 2. Thermal parameters

Symbol	Parameter			Value	Unit
R <sub>th(j-c)</sub>	Junction to case	TO	-220FPAC	6	° C/W

#### Table 3. Static electrical characteristics

Symbol	Parameter	Test conditions		Min	Тур	Max	Unit
I <sub>B</sub> <sup>(1)</sup>	Reverse leakage current	$T_j = 25^\circ C$	VV			1	μA
'R`´	IR V Neverse leakage current	$T_j = 125^\circ C$	V <sub>R</sub> = V <sub>RRM</sub>		20	200	μΑ
V <sub>F</sub> <sup>(2)</sup>	V <sub>F</sub> <sup>(2)</sup> Forward voltage drop		l <sub>⊏</sub> = 10 A		1.5	1.7	V
۷F	T <sub>j</sub>	$T_j = 125^\circ C$	F = 10 A		1.15	1.35	v

1. Pulse test:  $t_p = 5 \text{ ms}, \delta < 2\%$ 

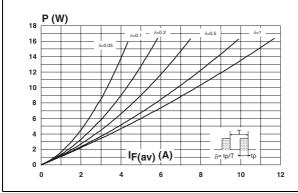
2. Pulse test:  $t_p = 380 \ \mu s, \ \delta < 2\%$ 

To evaluate the conduction losses use the following equation: P = 1.05 x  ${I_{F(AV)}}$  + 0.03  ${I_{F}}^2_{(RMS)}$ 

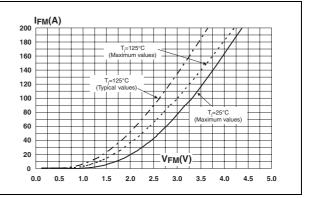
#### Table 4.Recovery characteristics

Symbol	Parameter	Test conditions		Min	Тур	Max	Unit
$t_{rr}$ Reverse recovery time $T_j = 25^{\circ} C$ $\frac{I_j}{I_j}$		T - 25° C	I <sub>F</sub> = 0.5 A, I <sub>rr</sub> = 0.25 A I <sub>R</sub> = 1 A		15	20	ns
		I <sub>F</sub> = 1 A, V <sub>R</sub> = 30 V dI <sub>F</sub> /dt = -50 A/μs			40	115	
t <sub>fr</sub>	Forward recovery time	$T_{j} = 25^{\circ} C \qquad \begin{array}{l} I_{F} = 10 \text{ A, } dI_{F}/dt = 100 \text{ A/}\mu\text{s} \\ V_{FR} = 1.1 \text{ x } V_{Fmax} \end{array}$				140	ns
V <sub>FP</sub>	Peak forward voltage	$T_j = 25^{\circ} C$ $I_F = 10 A$ , $dI_F/dt = 100 A/\mu s$				3	V
I <sub>RM</sub>	Reverse recovery current	T. – 125° C	$F_j = 125^{\circ} C$ $I_F = 10 \text{ A}, V_{CC} = 200 \text{ V}$ $dI_F/dt = 200 \text{ A/}\mu\text{s}$		6.2	8	А
S <sub>factor</sub>	Softness factor	$i_j = 120^{\circ}$ C			0.3		

### Figure 1. Conduction losses versus average forward current



### Figure 2. Forward voltage drop versus forward current





## Figure 3. Relative variation of thermal impedance junction to case versus pulse duration



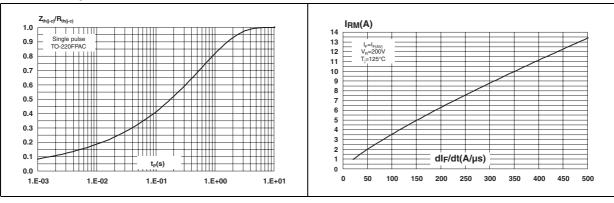


Figure 5. Reverse recovery time versus dl<sub>F</sub>/dt (typical values)

Figure 6. Reverse recovery charges versus dl<sub>F</sub>/dt (typical values)

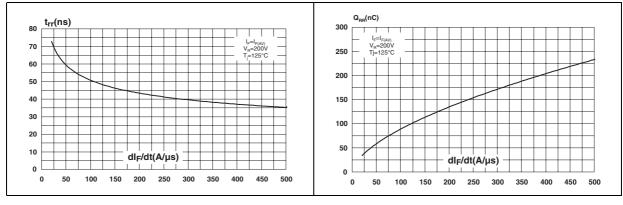
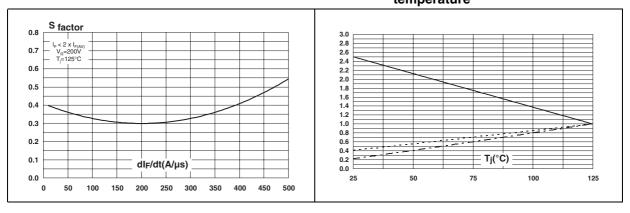


Figure 7. Reverse recovery softness factor versus dl<sub>F</sub>/dt (typical values)

Figure 8. Relative variations of dynamic parameters versus junction temperature



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### Figure 9. Transient peak forward voltage versus dl<sub>F</sub>/dt (typical values)

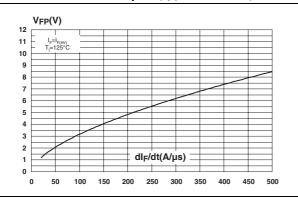
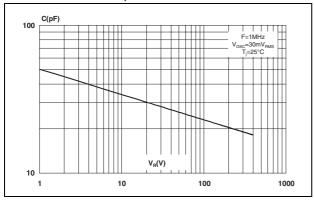
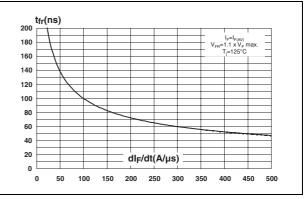


Figure 11. Junction capacitance versus reverse voltage applied (typical values)



### Figure 10. Forward recovery time versus dl<sub>F</sub>/dt (typical values)

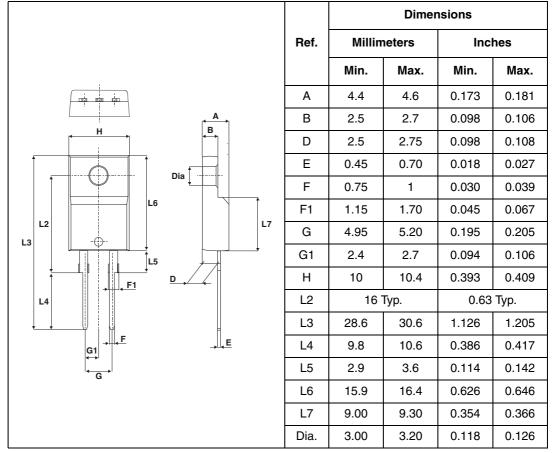




### 2 Package information

- Epoxy meets UL94, V0
- Cooling method: by conduction (C)
- Recommended torque calue: 0.8 Nm
- Maximum torque value: 1.0 Nm

Table 5.TO-220FPAC Dimensions



In order to meet environmental requirements, ST offers these devices in ECOPACK® packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the package and on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at: www.st.com.

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### **3** Ordering information

Ordering type	Marking	Package	Weight	Base qty	Delivery mode
STTH1004FP	STTH1004	TO-220FPAC	1.8 g	50	Tube

### 4 Revision history

Date	Revision	Description of Changes
24-May-2005	1	First issue.



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